


**Resin-moulded semiconductor hybrid module and manufacturing method thereof**

Patent Number: EP0936671

Publication  
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Requested  
Patent: ☐ EP0936671Application  
Number: EP19990101733 19990211Priority Number  
(s): JP19980029491 19980212IPC  
Classification: H01L25/16; H01L23/433EC  
Classification: H01L25/16H, H01L23/433EEquivalents: ☐ JP11233712, ☐ US6291880Cited  
Documents: EP0774782; US5699609; US5077595; JP8298299**Abstract**

A semiconductor device includes a main circuit part having a semiconductor device formed on an electrode plate (13) of a lead frame and a control circuit part having protective functions, which is integrally molded by a resin mold part (30) into an integral mold structure. 

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